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## FACSIMILE COVER SHEET

To: Commissioner for Patents	Total Pages Sent: 7
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Facsimile Number: (571) 273-8300	Transmission Date: June 6, 2006

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Su, *et al.* Docket No.: TSM03-0150  
Serial No: 10/675,862 Art Unit: 2823  
Date Filed: September 30, 2003 Examiner: Fernando L. Toledo  
Title: Apparatus and Method for Manufacturing a Semiconductor Wafer with Reduced Delamination and Peeling

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- Certification of Facsimile Transmission (1 page)
- Response Under 37 C.F.R. § 1.116 (6 pages)

Respectfully submitted,

Kristy Engeldahl  
Legal Assistant

Confirmation Respectfully Requested

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Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**RESPONSE UNDER 37 C.F.R. § 1.116**

Dear Sir:

The following amendments and remarks are presented in response to the Examiner's  
Final Office Action mailed April 4, 2006. Please amend the above-referenced application as  
follows.